

Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NOVLP068/NVLS-000818	NEW
	Applicant:	
	Koos et al.	
	Filing Date	Group
	HEREWITH	UNASSIGNED

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
LV	A1	6,342,733	1/29/02	Hu et al.			
LV	A2	5,486,234	1/23/96	Contolini et al.			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
LV	C1	Mori et al., "Metal Capped Cu Interconnection Technology by Chemical Mechanical Polishing," VMIC Conference, 1996, 487-492
LV	C2	Hu et al., "Reduced Electromigration of Cu Wires by Surface Coating," Applied Physics Letters, Vol. 81, No. 10, (2002), 1782-1784
LV	C3	E.G. Colgan, "Selective CVD-W for Capping Damascene Cu Lines," Thin Solid Films, 262, (1995), 120-123
LV	C4	Enhanced Copper Metallurgy for BEOL Application, IBM Technical Disclosure Bulletin, Vol. 33, No. 5, (1990), 217-218
Examiner LAN VINI		Date Considered 8/1/05

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.